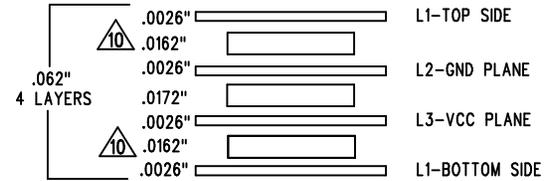


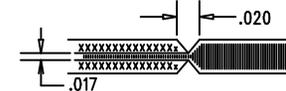
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	3	3RD PROTOTYPE	JOHN C.	03-10-14

LAYER STRUCTURE for FR-370HR, DIELECTRIC CONSTANT=4.7



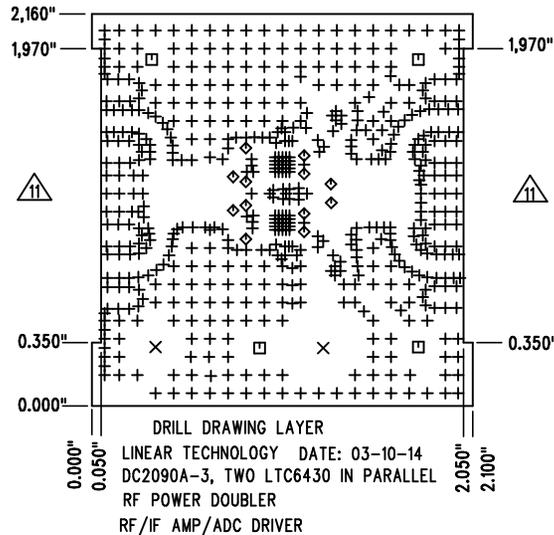
NOTES: UNLESS OTHERWISE SPECIFIED

- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, ISOLA FR-370HR OR EQUIVALENT.
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. CU ON THE OUTER LAYERS AND 2 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
- DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
- FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN.
-GOLD IMMERSION BOTH SIDES.
-FOR SILKSCREENS: USE WHITE NON-CONDUCTIVE INK.
- CONTROLLED 50 OHM +/-5% IMPEDANCE FOR LAYERS 1-2, 4-3 USING 0.027" TRACE
- DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE. PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
- PCBS ARE TO BE RoHS COMPLIANT.
- SCORING FOR PANELIZED PCB (PRODUCTION FAB ONLY):



10. SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.

11. INNER AND OUTER LAYER COPPER SHALL BE EXPOSED ALONG BOARD EDGES. DO NOT MODIFY INNER LAYER COPPER BACKOFF OUTLINE (SMA CONNECTOR).



SIZE	QTY	SYM	PLATED	TOL
0.008	566	+	YES	+/-0.003
0.215	2	X	YES	+/-0.003
0.095	4	□	YES	+/-0.003
0.01	12	◇	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES: 0.XX" = ±0.01" 0.XXX" = ±0.005" INTERPRET DIM AND TOL PER ASME Y14.5M-1994 THIRD ANGLE PROJECTION	APPROVALS		 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY
	PCB DES.	AK.	
	APP ENG.	JOHN C.	TITLE: FABRICATION DRAWING
			RF POWER DOUBLER RF/IF AMP/ADC DRIVER
	SIZE	IC NO. TWO LTC6430AUF IN PARALLEL	REV
	N/A	DEMO CIRCUIT 2090A	3
	SCALE = NONE	FILENAME: DC2090A-3.PCB	SHT 1 OF 1